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**PRODUCT BULLETIN # 16499**Generic Copy

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**Issue Date:** 23-Jul-2010**TITLE:** Shipping Jar change at ON Semiconductor Pocatello, Idaho site.**PROPOSED FIRST SHIP DATE:** 02-Aug-2010**AFFECTED CHANGE CATEGORY(S):** Shipping**FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:**Contact your local ON Semiconductor sales office or <[nolan.briscoe@onsemi.com](mailto:nolan.briscoe@onsemi.com)>**NOTIFICATION TYPE:**ON Semiconductor considers this change approved unless specific conditions of acceptance are provided in writing. To do so, contact <[quality@onsemi.com](mailto:quality@onsemi.com)>.**DESCRIPTION AND PURPOSE:**

On Semiconductor in Pocatello is changing the 200mm shipping jar and liners used to ship thinned wafers from an un-specified opaque jar to a Black ESD safe Jar. This change is to improve the ESD handling of the wafers and to integrate to the ON Semiconductor global standard shipping container.

The new jars are procured from ePAK. The ePAK part numbers are listed below.

<u>Description</u>	<u>ePAK part number</u>
Black 200mm Jar	ejr-235-51-eM-20
Black Wafer Separator	eil8-200-0.13-eM-20
Liner 200 mm wafers	eFL8-712-50-13-eM-04H
Cushion 200 mm wafersq	eFD8-200-3-eM-04H



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**List of affected General Parts:**

13963-812-XDW
19784-001-XDW